



Click [here](#) for the 3D model.

**General Information**

|                         |   |
|-------------------------|---|
| Series                  | KPS LDD Mil SMPS PRF49470   |
| Style                   | Leaded Stacked Chip   |
| Description             | Low ESR, High Current Stacked Ceramic Chips   |
| Features                | Low ESR, High Current   |
| RoHS                    | No  |
| Prop 65                 | <b>WARNING:</b> Cancer and reproductive harm - <a href="https://www.p65warnings.ca.gov/">https://www.p65warnings.ca.gov/</a>  |
| SCIP Number             | 2499890a-0e07-42ff-98a1-bd02d3b7c2ec  |
| Termination             | 60/40 Solder Coated   |
| Lead                    | J Leads   |
| Failure Rate            | N/A   |
| Testing and Reliability | Level B   |
| Qualifications          | MIL-PRF-49470   |
| Notes                   | Note: Number of chips in stack depends on design. Note: Turn Radius For Lead Extension Is 0.1 Radians (Typical). Note: Lead alignment within pin rows shall be within ±0.13 mm. |

| Dimensions |                    |
|------------|--------------------|
| D          | 6.335mm +/-0.645mm |
| L          | 1.78mm +/-0.25mm   |
| T          | 1.397mm MAX        |
| S          | 2.54mm TYP         |
| F          | 0.254mm +/-0.051mm |
| A          | 16.51mm MAX        |
| C          | 6.35mm +/-0.635mm  |
| E          | 7.62mm MAX         |
| LO         | 1.586mm MAX        |
| LW         | 0.508mm +/-0.051mm |
| MP         | 1.27mm MIN         |

| Specifications                  |              |
|---------------------------------|--------------|
| Capacitance                     | 3.3 uF       |
| Tolerance                       | 10%          |
| Voltage DC                      | 100 VDC      |
| Dielectric Withstanding Voltage | 250 VDC      |
| Temperature Range               | -55/+125°C   |
| Temp. Coefficient               | BX           |
| Dissipation Factor              | 2.5%         |
| Insulation Resistance           | 303.03 MOhms |

| Packaging Specifications |             |
|--------------------------|-------------|
| Packaging                | Waffle, Box |
| Packaging Quantity       | 64          |

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